EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	1	10/785615	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	ON	2008/04/29 17:44
S3	1	S1 and ((atomic adj layer) atomic)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	ON	2008/04/29 17:49
S5	30247	(ruthenium "Ru") and (copper "Cu") and (Iodine "I") and (wafer substrate carrier)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	ON	2008/04/29 18:49
S6	17061	S5 and (@ad<"20030225" @rlad<"20030225")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	ON	2008/04/29 18:50
S7	6142	S6 and (passivat$3 seed barrier)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	ON	2008/04/29 18:54
S8	1209	S6 and (passivat$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	ON	2008/04/29 18:54
S9	2254	S6 and seed	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	ON	2008/04/29 18:54
S10	4288	S6 and barrier	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	ON	2008/04/29 18:54

S11	140	S8 and S9 and S10	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	ON	2008/04/29 18:55
S12	140	S11 and deposition	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	ON	2008/04/29 18:55
S13	1	S12 and ruthenium and copper and iodine	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	ON	2008/04/29 18:55
S14	136	S12 and conduct$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	ON	2008/04/29 19:07
S15	10	(("6153443") or ("20030119307") or ("20020030297") or ("20020132466") or ("6831003") or ("6528409") or ("20030057414") or ("20030049913") or ("20020094673") or ("6312874")).PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	OFF	2008/04/29 19:16
S16	9898	438/627,643,652-654,628,629,638,641-644,674,687,678,256,299,485.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	ON	2008/04/29 19:28
S17	381	S16 and S5	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	ON	2008/04/29 19:28
S18	0	S16 and S13	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	ON	2008/04/29 19:28
S19	17	S16 and ruthenium and copper and iodine	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	ON	2008/04/29 19:28

S20	11	S19 and (@ad<"20030225" @rlad<"20030225")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	ON	2008/04/29 19:28
S21	10	((("6153443") or ("20030119307") or ("20020030297") or ("20020132466") or ("6831003") or ("6528409") or ("20030057414") or ("20030049913") or ("20020094673") or ("6312874")).PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	OFF	2008/04/30 12:42
S22	0	S21 and ((ruthenium "Ru") and (copper "Cu") and (Iodine "I.sub.2"))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	ON	2008/04/30 12:42
S23	0	S21 and (Iodine "I.sub.2")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	ON	2008/04/30 12:43
S24	21867	(wafer substrate carrier) same (ruthenium "Ru")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	ON	2008/04/30 12:43
S25	2853	(wafer substrate carrier) same ((ruthenium "Ru") near2 (layer film plate))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	ON	2008/04/30 12:44
S26	602	S25 and (((ruthenium "Ru") near2 (layer film plate)) same ((copper "Cu") near2 (layer film plate)))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	ON	2008/04/30 12:45
S27	4	S26 and (((copper "Cu") near2 (layer film plate)) same ((iodine "I" "I.sub.2") near2 (layer film plate)))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	ON	2008/04/30 12:46
S28	36	S26 and ((iodine "I" "I.sub.2") near2 (layer film plate sheet))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	ON	2008/04/30 13:53

S29	32	S28 not S27	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	ON	2008/04/30 13:53
S30	7	S29 and (@ad<"20030225" @rlad<"20030225")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	ON	2008/04/30 13:53
S31	2	S26 and ((iodine "I.sub.2") near2 (layer film plate sheet))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	ON	2008/04/30 14:19
S32	1979	(wafer substrate carrier) and ((iodine "I.sub.2") near2 (layer film plate sheet))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	ON	2008/04/30 14:20
S34	9	S32 and ((ruthenium "Ru") near2 (layer film plate sheet))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	ON	2008/04/30 14:21
S35	110	S32 and ((copper "Cu") near2 (layer film plate sheet))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	ON	2008/04/30 14:21
S36	4	S34 and S35	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	ON	2008/04/30 14:21
S37	86	S32 and ((ruthenium "Ru") and (copper "Cu"))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	ON	2008/04/30 14:31
S38	53	S37 not (S30 S34 S36) and (@ad<"20030225" @rlad<"20030225")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	ON	2008/04/30 14:31

S39	493	438/686.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	ON	2008/04/30 14:52
S40	46	S38 and (conduct$3 connect$3 contact$3 intercon??ct$3 inter-con??ct?$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	ON	2008/04/30 14:55
S41	7	S38 not S40	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	ON	2008/04/30 14:58
S42	16	("3844160" | "3864628" | "4112737" | "4218298" | "4347732" | "4354308" | "4931851" | "4935181" | "4947104" | "4953387" | "5394735" | "5417821" | "5431883").PN. OR ("6155100").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/04/30 15:08
S43	2094	(wafer substrate carrier) and ((iodine "I.sub.2") near2 (layer film plate sheet surface)) and (conduct$3 connect$3 contact$3 intercon??ct$3 inter-con??ct?$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	ON	2008/04/30 15:11
S44	123	S43 and ((ruthenium "Ru") and (copper "Cu"))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	ON	2008/04/30 15:12
S45	78	S44 and (@ad<"20030225" @rlad<"20030225")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	ON	2008/04/30 15:12
S46	32	S45 not (S30 S34 S36 S40)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	ON	2008/04/30 15:12
S47	191	S43 and (ruthenium "Ru")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	ON	2008/04/30 15:45
S48	652	S43 and (copper "Cu")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	ON	2008/04/30 15:45

S49	370	(S47 S48) not (S30 S34 S36 S40 S46) and (@ad<"20030225" @rlad<"20030225")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	ON	2008/04/30 15:46
S50	0	S49 and ((ruthenium "Ru") with (adhesiv$3 barrier))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	ON	2008/04/30 15:47
S51	0	S49 and ((ruthenium "Ru") same (adhesiv$3 barrier))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	ON	2008/04/30 15:47
S54	68	S49 and ((copper "Cu") same (Iodine "I.sub.2"))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	ON	2008/04/30 15:51
S56	51	S54 and iodine	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	ON	2008/04/30 16:03
S58	1586	(conduct$3 connect$3 contact$3 intercon??ct$3 inter-con??ct?$3) and (iodine near2 (layer surface film plate)) and (@ad<"20030225" @rlad<"20030225")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	ON	2008/04/30 16:14
S59	75	S58 and ((copper "Cu") near2 (layer surface film plate))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	ON	2008/04/30 16:15
S61	77778	(conduct$3 connect$3 contact$3 intercon??ct$3 inter-con??ct?$3) and ((copper "Cu") near2 (layer surface film plate)) and (@ad<"20030225" @rlad<"20030225")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	ON	2008/04/30 16:17
S62	4145	(conduct$3 connect$3 contact$3 intercon??ct$3 inter-con??ct?$3) and ((Ruthenium "Ru") near2 (layer surface film plate)) and (@ad<"20030225" @rlad<"20030225")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	ON	2008/04/30 16:17

S63	45	S59 not (S30 S34 S36 S40 S46 S56)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	ON	2008/04/30 16:18
S64	0	S58 and S61 and S62	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	ON	2008/04/30 16:18
S65	17	S63 and (iodine adj (layer surface film plate))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	ON	2008/04/30 16:20
S66	162	(Copper "Cu") and (iodine near3 (passivat$3 protect$3 prevent$3)) and (@ad<"20030225" @rlad<"20030225")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	ON	2008/04/30 16:29
S67	153	S66 not (S30 S34 S36 S40 S46 S56 S65)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	ON	2008/04/30 16:30
S68	8	S67 and (ruthenium "Ru")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	ON	2008/04/30 16:30
S69	109	S67 and (conduct$3 connect$3 contact$3 intercon??ct$3 inter-con??ct?$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	ON	2008/04/30 16:34
S70	129	(Copper "Cu") and (iodine near3 coat$3) and (@ad<"20030225" @rlad<"20030225")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	ON	2008/04/30 16:41
S71	102	S70 not (S30 S34 S36 S40 S46 S56 S65 S69)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	ON	2008/04/30 16:41

S72	44	S66 not (S30 S34 S36 S40 S46 S56 S65 S69 S71)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	ON	2008/04/30 16:58
S73	2587	(Copper "Cu") and (iodine same (passivat$3 protect$3 prevent$3)) and (@ad<"20030225" @rlad<"20030225")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	ON	2008/04/30 17:00
S74	2380	S73 not (S30 S34 S36 S40 S46 S56 S65 S69 S71 S72)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	ON	2008/04/30 17:01
S75	483	S74 and ((corros$3 degradat$3 oxidiz$3 oxidat$3) with (metal$3 copper "Cu"))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	ON	2008/04/30 17:06

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